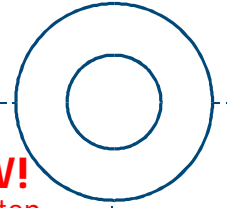




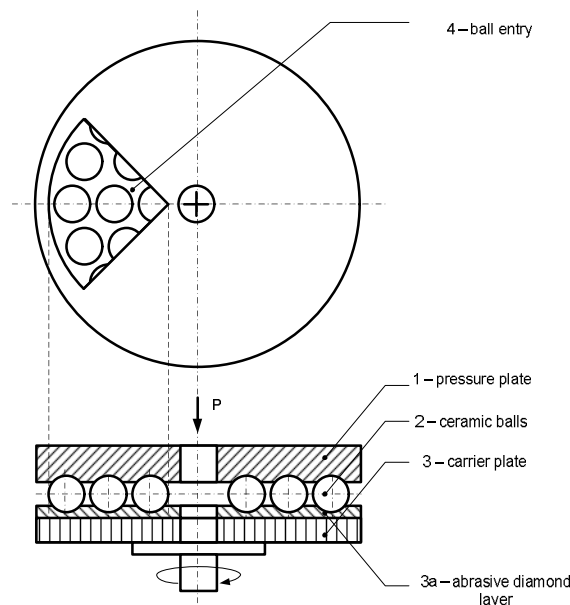
► Technical Data

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Patent Application Patent Application Patent Application



Ceramic Ball Grinding With Bonded Diamond Grain

Ball grinding and ball fine grinding operations are carried out using the following production principle:



Process Advantages:

- The diamond grains are firmly held inside a bonding matrix
- Use of honing oils as coolant
- High Process Stability
- Low quality variations within a batch
- Stock removal rate up to 160 μ m/h (dependant on ball material)
- Reduced pressure plate wear
- Minimised environmental impact through the use of filter technology
- Large batch sizes possible when used in conjunction with ball grinding machines with magazines

Work piece materials:

Ball Material: Si_3N_4 , ZrO_2 , Al_2O_3 , WC, SiC

Initial ball state: All initial ball geometry that results from the manufacturing process can be ground.

Product Range :

Abrasive Grain: Synthetic Diamond (65D)
 Grain Size FEPA: D46 to D91
 Structure: 00
 Bonding: XA

Available Product Dimensions :

(ISO-Form: 2A2, Abrasive layer mounted on carrier plate)

Outer Diameter (D)[mm]	Abrasive Layer Depth (X) [mm]	Internal Diameter(H) [mm]
100	5, 10, 15, 20	30
200		30; 50
300		30; 50
400		30; 50; 150

Application Example:

Ball grinding wheel 200 x 25 x 30, X=5, W=50, 5 Grooves

Ball Grinding:

65D 91 V00 B XA 100

Si_3N_4 Balls, shape: round
 Batch Size: 300 pieces
 Initial dia.: 5,34 mm
 Final dia.: 5,16 mm
 Stock removal: 180 μm
 Grinding time: 3,5 hours
 Stock removal rate: 51 $\mu\text{m}/\text{h}$
 Pressure plate: Steel
 Coolant: Honing Oil EMOL[®]-O-HON 920 NV
 Roundness: < 0,5 μm



Si_3N_4 – Ball before and after grinding

Should you require any further information please contact:

Dr. Michael Pöttsch